

74F269

8-bit bidirectional binary counter

Rev. 6 — 14 December 2011

Product data sheet

1. General description

The 74F269 is a fully synchronous 8-stage up/down counter featuring a preset capability for programmable operation, carry look-ahead for easy cascading and a $\overline{U/D}$ input to control the direction of counting. All state changes, whether in counting or parallel loading, are initiated by the rising edge of the clock.

2. Features and benefits

- Synchronous counting and loading
- Built-in look-ahead carry capability
- Count frequency 115 MHz (typical)
- Supply current 95 mA (typical)

3. Ordering information

Table 1. Ordering information

Type number	Package			
	Temperature range	Name	Description	Version
N74F269D	0 °C to 70 °C	SO24	plastic small outline package; 24 leads; body width 7.5 mm	SOT137-1
N74F269DB	0 °C to 70 °C	SSOP24	plastic shrink small outline package; 24 leads; body width 5.3 mm	SOT340-1



4. Functional diagram

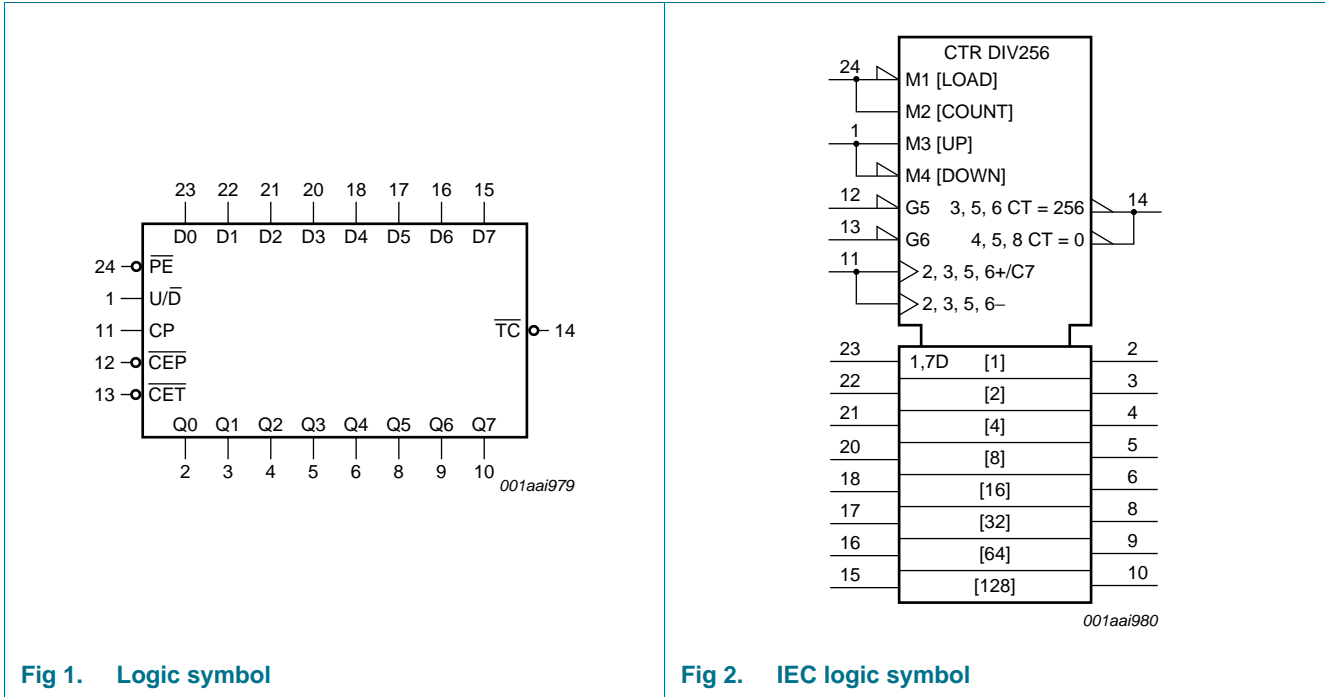
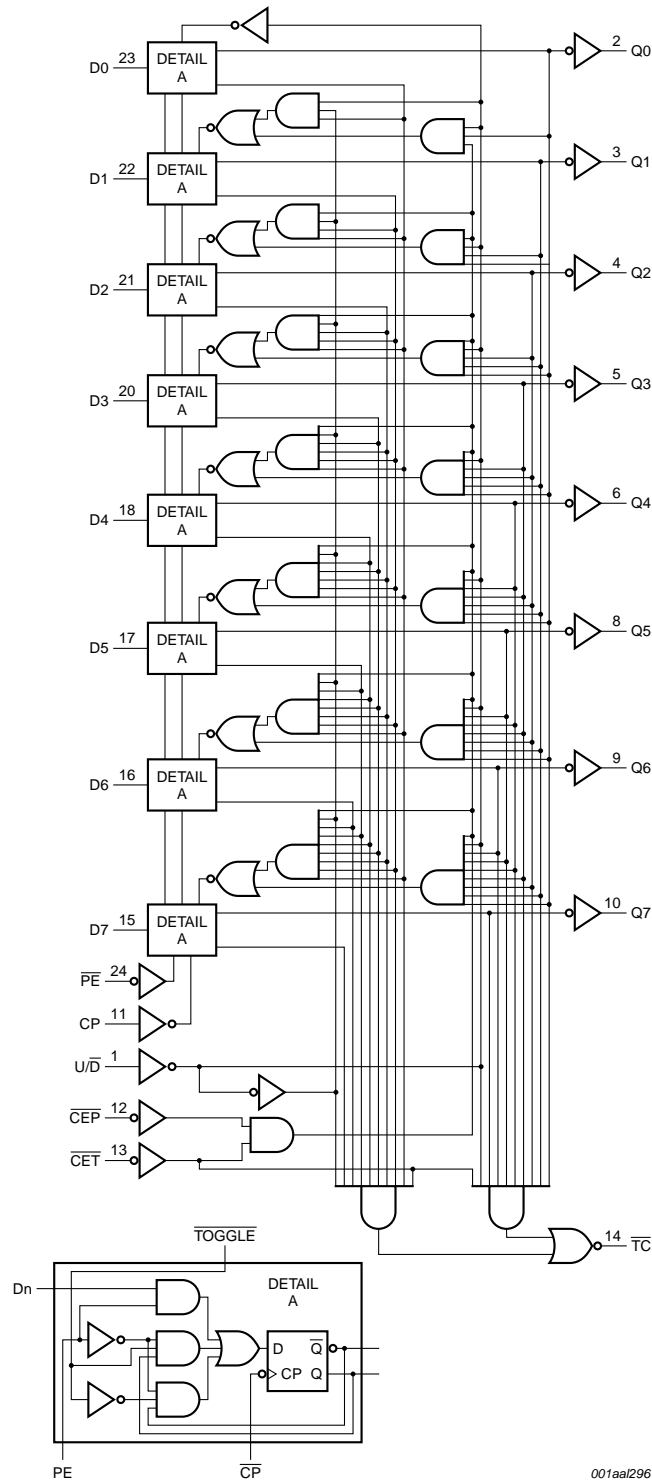


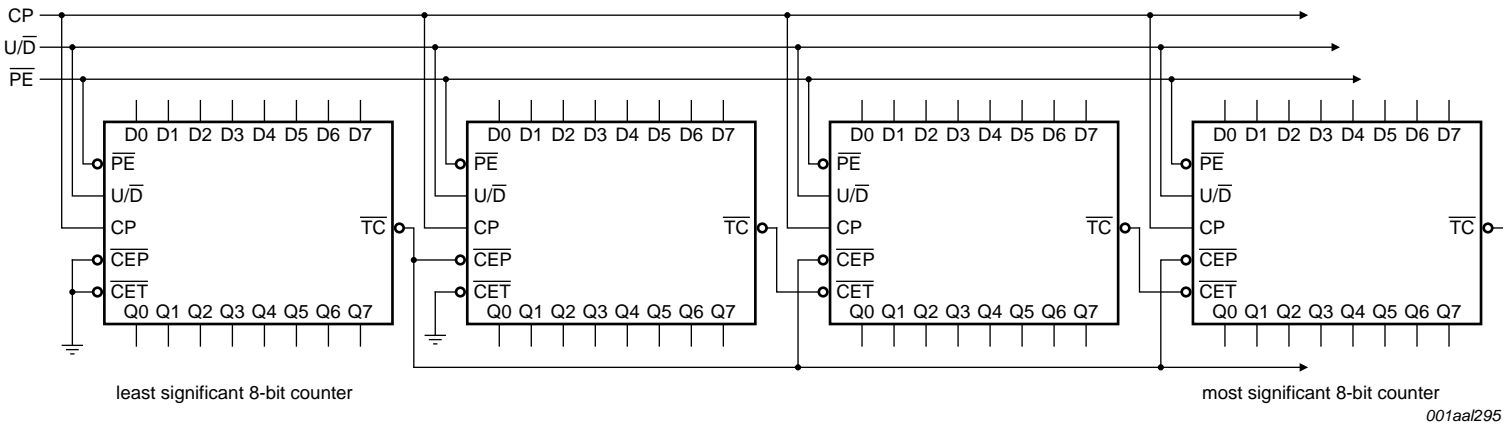
Fig 1. Logic symbol

Fig 2. IEC logic symbol



001aa/296

Fig 3. Logic diagram



001aal295

Fig 4. Synchronous multistage counting scheme

6. Functional description

6.1 Function table

Table 3. Function table^[1]

Operating modes	Input						Output	
	CP	U/D	CEP	CET	PE	Dn	Qn	TC
Parallel load (Dn to Qn)	↑	X	X	X	l	l	L	*
	↑	X	X	X	l	h	H	*
Count up (increment)	↑	h	l	l	h	X	count up	*
Count down (decrement)	↑	l	l	l	h	X	count down	*
Hold (do nothing)	↑	X	h	l	h	X	qn	*
	↑	X	X	h	h	X	qn	H

[1] H = HIGH voltage level steady state

h = HIGH voltage level one set-up time prior to the LOW-to-HIGH clock transition

L = LOW voltage level steady state

l = LOW voltage level one set-up time prior to the LOW-to-HIGH clock transition

qn = Lower case letters indicate state of referenced output prior to the LOW-to-HIGH clock transition

X = don't care

↑ = LOW-to-HIGH clock transition

* = The \overline{TC} is LOW when \overline{CET} is LOW and the counter is at terminal count

Terminal count up is with all Qn outputs HIGH and terminal count down is with all Qn outputs LOW.

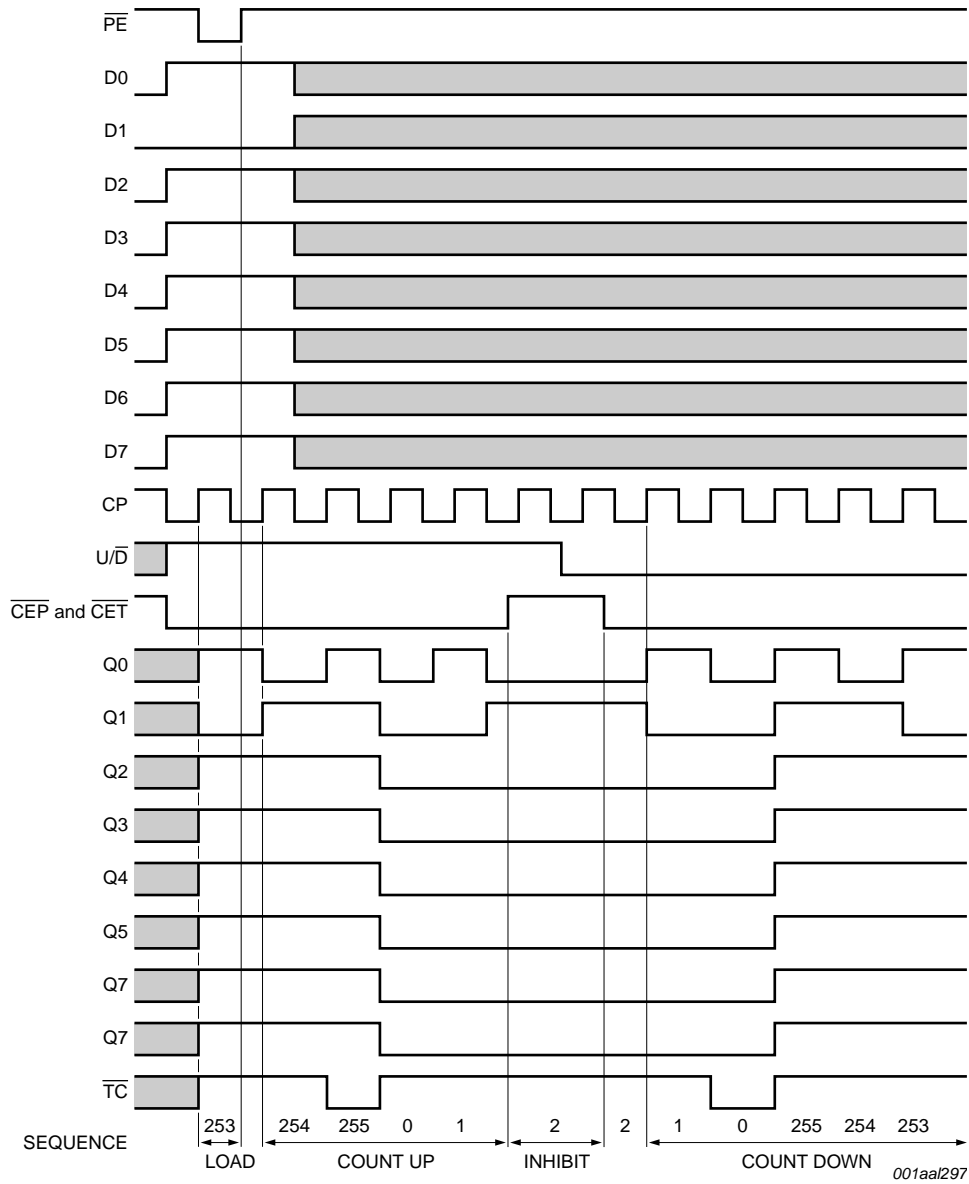


Fig 6. Typical timing sequence

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CC}	supply voltage		-0.5	+7.0	V
V_I	input voltage		[1] -0.5	+7.0	V
V_O	output voltage	output in HIGH-state	[1] -0.5	+5.5	V
I_{IK}	input clamping current	$V_I < 0$ V	-30	+5	mA
I_O	output current	output in LOW-state	-	40	mA
T_{amb}	ambient temperature	in free air	[2] 0	70	°C
T_{stg}	storage temperature		-65	+150	°C

[1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] The performance capability of a high-performance integrated circuit in conjunction with its thermal environment can create junction temperatures which are detrimental to reliability. The maximum junction temperature of this integrated circuit should not exceed 150 °C.

8. Recommended operating conditions

Table 5. Recommended operating conditions

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{CC}	supply voltage		4.5	5.0	5.5	V
V_{IH}	HIGH-level input voltage		2.0	-	-	V
V_{IL}	LOW-level input voltage		-	-	0.8	V
I_{IK}	input clamping current		-	-	-18	mA
I_{OH}	HIGH-level output current		-1	-	-	mA
I_{OL}	LOW-level output current		-	-	20	mA

9. Static characteristics

Table 6. Static characteristics

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		Unit
			Min	Typ ^[1]	Max	Min	Max	
V _{IK}	input clamping voltage	V _{CC} = 4.5 V; I _{IK} = -18 mA	-1.2	-0.73	-	-1.2	-	V
V _{OH}	HIGH-level output voltage	V _{CC} = 4.5 V; V _I = V _{IL} or V _{IH}	-	-	-	2.5	-	V
		V _{CC} = ±10 %; I _{OH} = -1 mA	-	-	-	2.5	-	V
		V _{CC} = ±5 %; I _{OH} = -1 mA	-	3.4	-	2.7	-	V
V _{OL}	LOW-level output voltage	V _{CC} = 4.5 V; I _{OL} = 20 mA; V _I = V _{IL} or V _{IH}	-	-	-	-	-	V
		V _{CC} = ±10 %	-	0.30	-	-	0.50	V
		V _{CC} = ±5 %	-	0.30	-	-	0.50	V
I _I	input leakage current	V _{CC} = 5.5 V; V _I = 7.0 V	-	-	-	-	100	μA
I _{IH}	HIGH-level input current	V _{CC} = 5.5 V; V _I = 2.7 V	-	-	-	-	20	μA
I _{IL}	LOW-level input current	V _{CC} = 5.5 V; V _I = 0.5 V	-	-	-	-	-0.6	mA
I _O	output current	V _{CC} = 5.5 V ^[2]	-	-	-	-60	-150	mA
I _{CC}	supply current	PE = CET = CEP = U/D = GND; V _{CC} = 5.5 V; CP = rising edge	-	-	-	-	-	-
		Dn: V _I = 4.5 V	-	93	-	-	120	mA
		Dn: V _I = GND	-	98	-	-	125	mA

[1] All typical values are measured at V_{CC} = 5 V.

[2] Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

10. Dynamic characteristics

Table 7. Dynamic characteristics

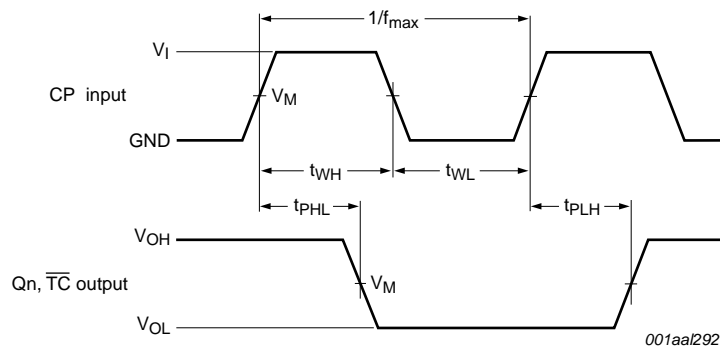
GND = 0 V; for test circuit, see Figure 13.

Symbol	Parameter	Conditions	25 °C; V _{CC} = 5.0 V			0 °C to 70 °C; V _{CC} = 5.0 V ± 0.5 V		Unit
			Min	Typ	Max	Min	Max	
t _{PLH}	LOW to HIGH propagation delay	CP to Qn; load; PE = LOW; see Figure 7	3.0	6.0	8.5	3.0	9.0	ns
		CP to Qn; count; PE = HIGH; see Figure 7	3.0	6.0	9.0	3.0	10.0	ns
		CP to TC; see Figure 7	4.5	6.5	9.5	4.0	10.5	ns
		CET to TC; see Figure 8	3.5	6.0	9.0	3.0	10.0	ns
		U/D to TC; see Figure 9	4.5	7.0	9.0	4.0	10.0	ns
t _{PHL}	HIGH to LOW propagation delay	CP to Qn; load; PE = LOW; see Figure 7	4.0	6.5	8.5	4.0	9.0	ns
		CP to Qn; count; PE = HIGH; see Figure 7	4.5	7.0	10.0	4.0	10.5	ns
		CP to TC; see Figure 7	5.0	6.5	9.5	5.0	10.0	ns
		CET to TC; see Figure 8	3.0	6.5	9.0	3.0	10.0	ns
		U/D to TC; see Figure 9	4.5	7.0	9.5	4.0	10.0	ns

Table 7. Dynamic characteristics ...continued
GND = 0 V; for test circuit, see Figure 13.

Symbol	Parameter	Conditions	25 °C; V _{CC} = 5.0 V			0 °C to 70 °C; V _{CC} = 5.0 V ± 0.5 V		Unit
			Min	Typ	Max	Min	Max	
t _{su(H)}	set-up time HIGH	Dn to CP; see Figure 10	3.5	-	-	2.5	-	ns
		\overline{PE} to CP; see Figure 10	5.5	-	-	5.5	-	ns
		\overline{CEP} or \overline{CET} to CP; see Figure 11	6.0	-	-	5.0	-	ns
		U/\overline{D} to CP; see Figure 12	8.0	-	-	6.5	-	ns
t _{su(L)}	set-up time LOW	Dn to CP; see Figure 10	3.5	-	-	2.5	-	ns
		\overline{PE} to CP; see Figure 10	6.5	-	-	6.5	-	ns
		\overline{CEP} or \overline{CET} to CP; see Figure 11	8.0	-	-	6.5	-	ns
		U/\overline{D} to CP; see Figure 12	6.5	-	-	6.5	-	ns
t _{h(H)}	hold time HIGH	Dn to CP; see Figure 10	1.0	-	-	0	-	ns
		\overline{PE} to CP; see Figure 10	0	-	-	0	-	ns
		\overline{CEP} or \overline{CET} to CP; see Figure 11	0	-	-	0	-	ns
		U/\overline{D} to CP; see Figure 12	0	-	-	0	-	ns
t _{h(L)}	hold time LOW	Dn to CP; see Figure 10	1.0	-	-	1.0	-	ns
		\overline{PE} to CP; see Figure 10	0	-	-	0	-	ns
		\overline{CEP} or \overline{CET} to CP; see Figure 11	0	-	-	0	-	ns
		U/\overline{D} to CP; see Figure 12	0	-	-	0	-	ns
t _{WH}	pulse width HIGH	CP; see Figure 7	4.0	-	-	4.0	-	ns
t _{WL}	pulse width LOW	CP; see Figure 7	4.5	-	-	5.0	-	ns
f _{max}	maximum frequency	see Figure 7	100	115	-	85	-	MHz

11. Waveforms

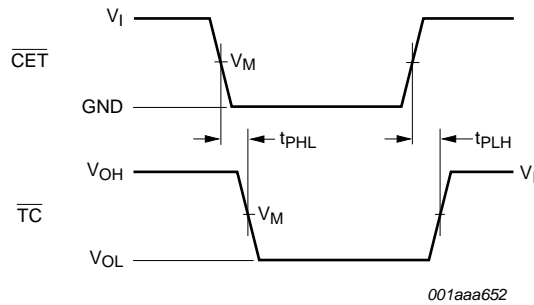


Measurement points are given in [Table 8](#).

V_M = 1.5 V

V_{OL} and V_{OH} are the typical output voltage levels that occur with the output load.

Fig 7. Clock (CP) to outputs (Qn, \overline{TC}) propagation delay, the clock pulse width

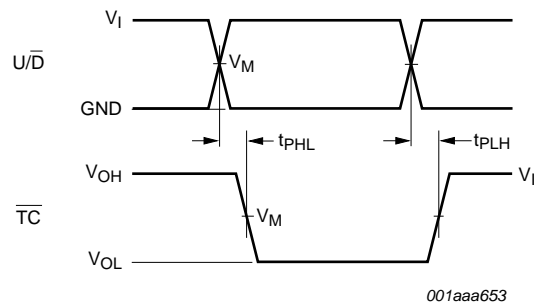


Measurement points are given in [Table 8](#).

$V_M = 1.5\text{ V}$

V_{OL} and V_{OH} are the typical output voltage levels that occur with the output load.

Fig 8. Input ($\overline{\text{CET}}$) to output ($\overline{\text{TC}}$) propagation delay

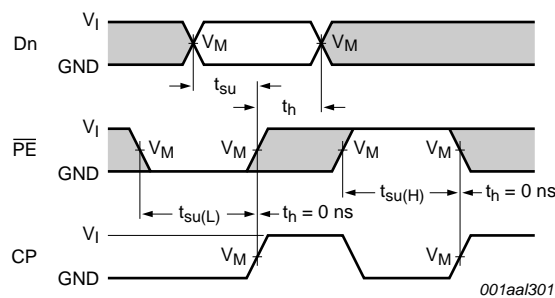


Measurement points are given in [Table 8](#).

$V_M = 1.5\text{ V}$

V_{OL} and V_{OH} are the typical output voltage levels that occur with the output load.

Fig 9. The up/down control input ($\overline{\text{U/D}}$) to output ($\overline{\text{TC}}$) propagation delay

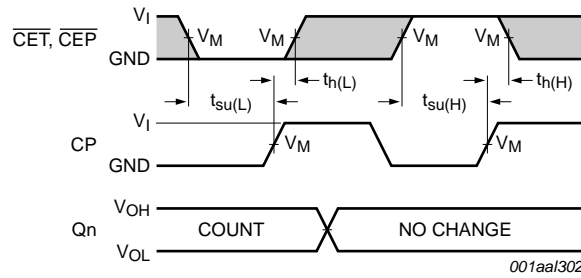


The shaded areas indicate when the input is permitted to change for predictable output performance.

Measurement points are given in [Table 8](#).

$V_M = 1.5\text{ V}$

Fig 10. Data input (Dn), parallel enable input ($\overline{\text{PE}}$) and clock input (CP) set-up and hold times



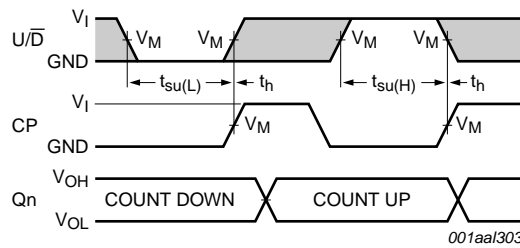
The shaded areas indicate when the input is permitted to change for predictable output performance.

Measurement points are given in [Table 8](#).

$V_M = 1.5\text{ V}$

V_{OL} and V_{OH} are the typical output voltage levels that occur with the output load.

Fig 11. Count enable inputs (\overline{CEP} and \overline{CET}) and clock input (CP) set-up and hold times



The shaded areas indicate when the input is permitted to change for predictable output performance.

Measurement points are given in [Table 8](#).

$V_M = 1.5\text{ V}$

V_{OL} and V_{OH} are the typical output voltage levels that occur with the output load.

Fig 12. Up/down count control input (U/\overline{D}) and clock input (CP) set-up and hold times

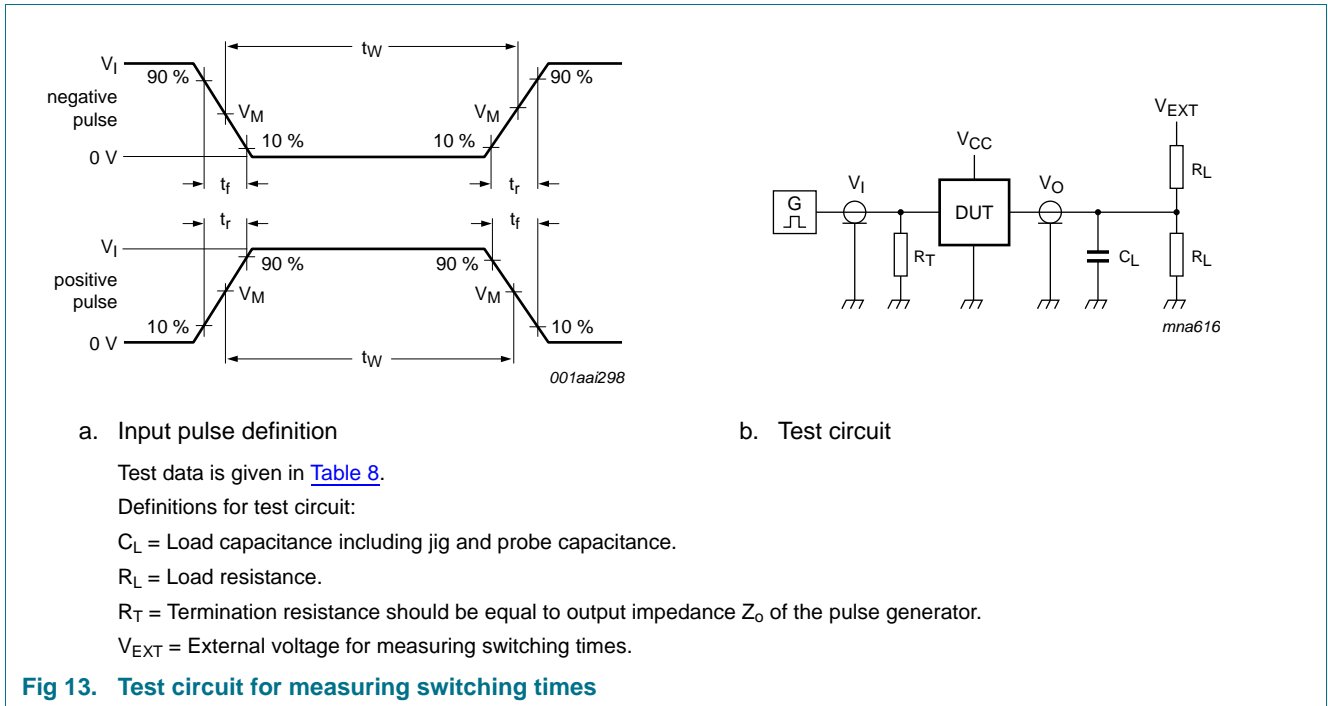


Fig 13. Test circuit for measuring switching times

Table 8. Test data

Input				Load		V_{EXT}		
V_I	f_I	t_W	t_r, t_f	C_L	R_L	t_{PHL}, t_{PLH}	t_{PZH}, t_{PHZ}	t_{PZL}, t_{PLZ}
3.0 V	1 MHz	500 ns	≤ 2.5 ns	50 pF	500 Ω	open	open	7.0 V

12. Package outline

SO24: plastic small outline package; 24 leads; body width 7.5 mm

SOT137-1

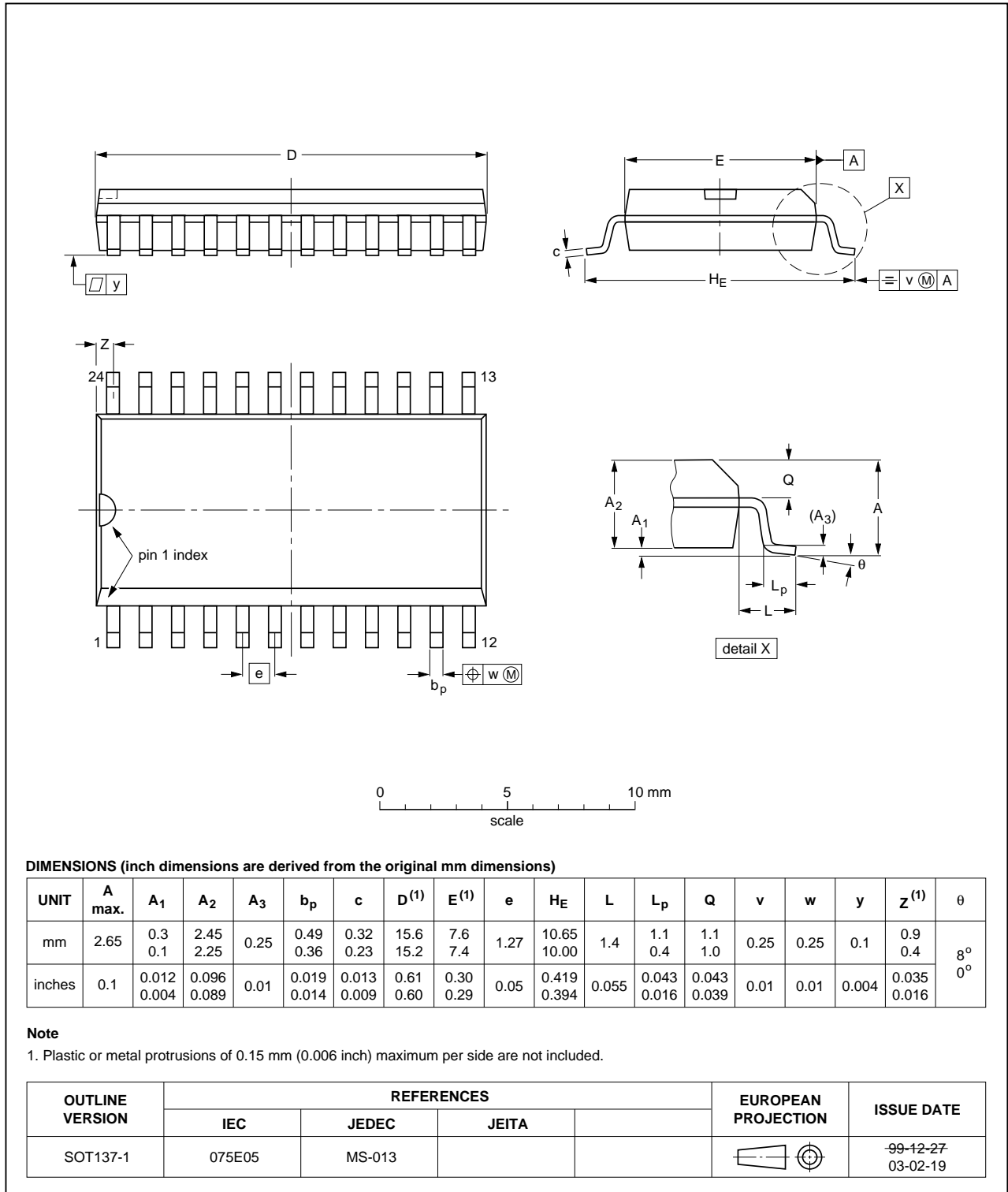


Fig 14. Package outline SOT137-1 (SO24)

SSOP24: plastic shrink small outline package; 24 leads; body width 5.3 mm

SOT340-1

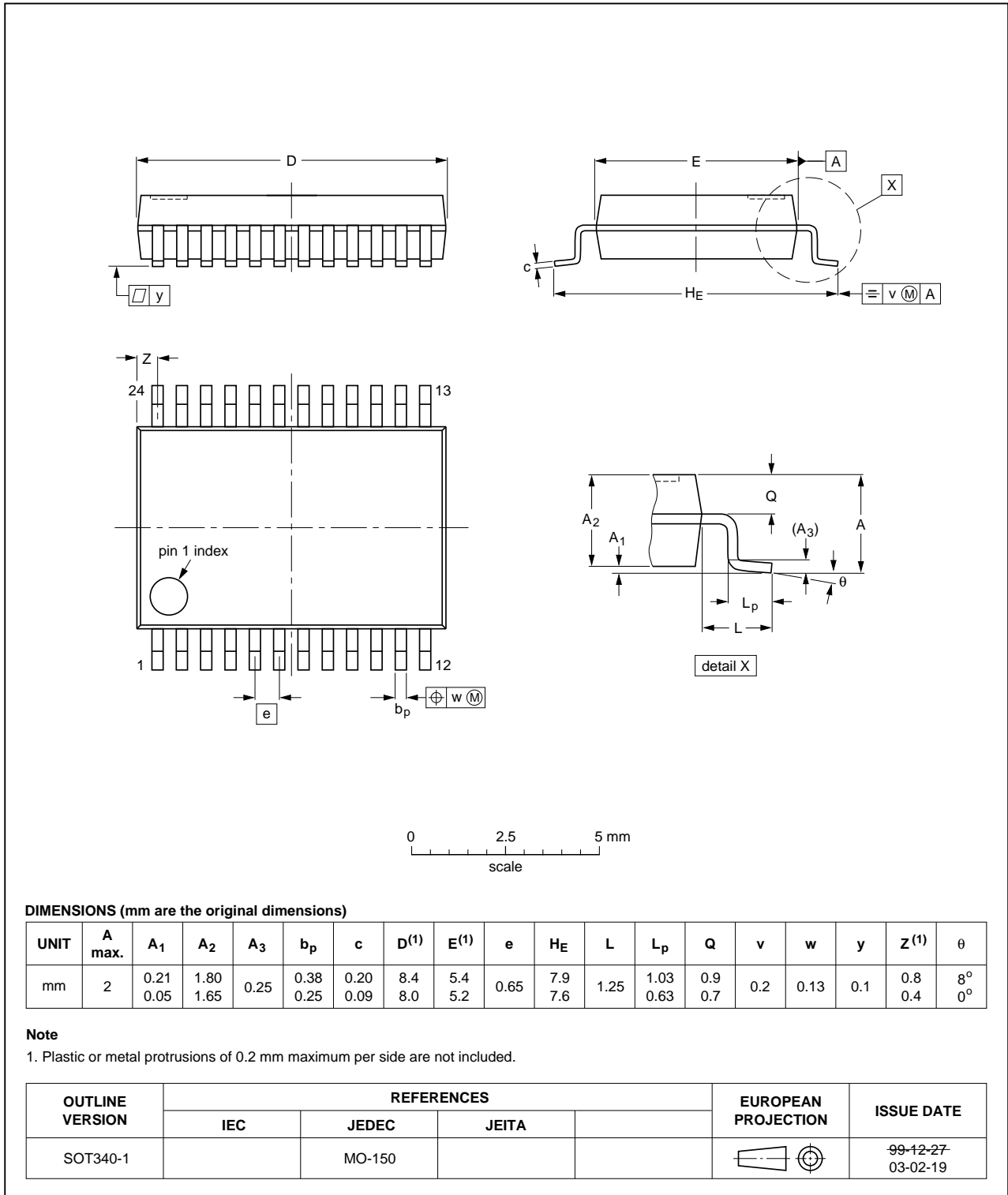


Fig 15. Package outline SOT340-1 (SSOP24)

13. Abbreviations

Table 9. Abbreviations

Acronym	Description
BiCMOS	Bipolar Complementary Metal-Oxide Semiconductor
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model

14. Revision history

Table 10. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74F269 v.6	20111214	Product data sheet	-	74F269 v.5
Modifications:	• Legal pages updated.			
74F269 v.5	20100325	Product data sheet	-	74F269 v.4
74F269 v.4	20100308	Product data sheet	-	74F269 v.3
74F269 v.3	20100126	Product data sheet	-	74F269 v.2
74F269 v.2	19960105	Product specification	-	74F269 v.1

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15.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
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[2] The term 'short data sheet' is explained in section "Definitions".

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